

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-29. (Canceled)

30. (Currently Amended) An apparatus for electrodeposited film formation comprising:

an electrolyte solution bath ~~in which~~ holding: (a) an electrolyte solution containing ions to constitute an electrodeposited film is held and wherein (b) an object to be treated of which at least the surface permits generation of charged particles when irradiated with a laser beam and onto which the electrodeposited film is to be deposited is held; and  
~~a laser device for irradiating the object to be treated positioned in the electrolyte solution with a pulse laser outputting a laser beam whose pulse width is less than a picosecond and which irradiates at least part of the object to be treated positioned in the electrolyte solution to thereby excite electrons in the laser-irradiated part to cause and form the electrodeposited film to be formed in~~ the laser-irradiated part.

31. (Original) An apparatus for electrodeposited film formation, according to Claim 30, further provided with:

an opposite electrode held separated from the object to be treated in the electrolyte solution; and

a power source for applying a bias voltage between the object to be treated and the opposite electrode.

32. (New) The apparatus according to Claim 30, wherein said electrolyte solution contains at least one plating metal selected from the group consisting of Cu, Pt, Zn, Ni, Cd, Cr, Sn, Au, Ag, Rh, Ru, Pb, Ti, Pd, Co, B, Ge, Al, In, Ir, Mo, W, V and Ta.

33. (New) The apparatus according to Claim 32, wherein said electrolyte solution contains at least one of Cu, Pt, Zn or Ni.

34. (New) The apparatus according to Claim 30, wherein the object to be treated comprises a metal selected from the group consisting of Au, Cu, Pt, Zn, Cd, CrSnAu, AgRh, Ru, Pb, TiPd, Co, B, Ge, Al, In, Ir, Mo, W, V, Ta, Ni, Sn and alloys thereof.

35. (New) The apparatus according to Claim 30, wherein the object to be treated comprises at least one of Au, Cu, Pt or Zn.

36. (New) The apparatus according to Claim 30, wherein said electrolyte solution is an aqueous solution.

37. (New) The apparatus according to Claim 36, wherein said aqueous solution contains 2 to 18% by weight plating metal.